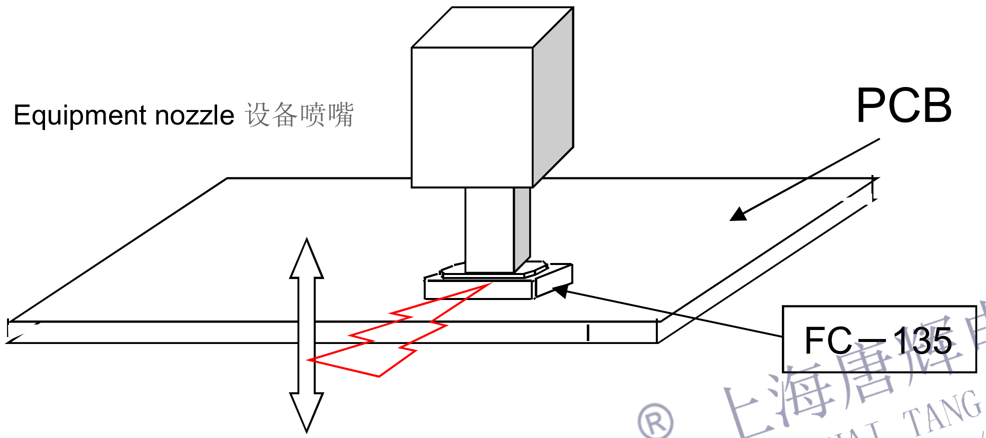
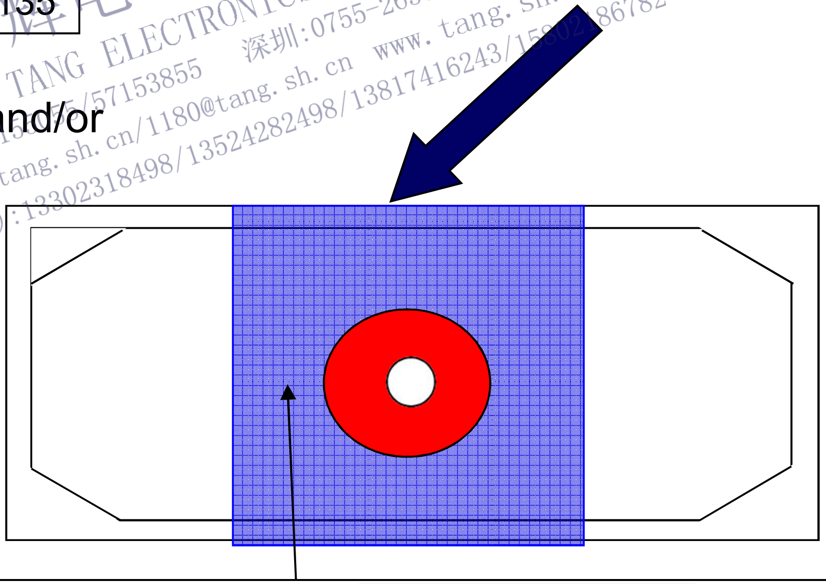
Appendix - Case .1附录-案例



Caused by mechanical impact by pushing PCB and/or PCB rebounding during attachment process
连接过程中推压PCB或PCB回弹引起的机械冲击

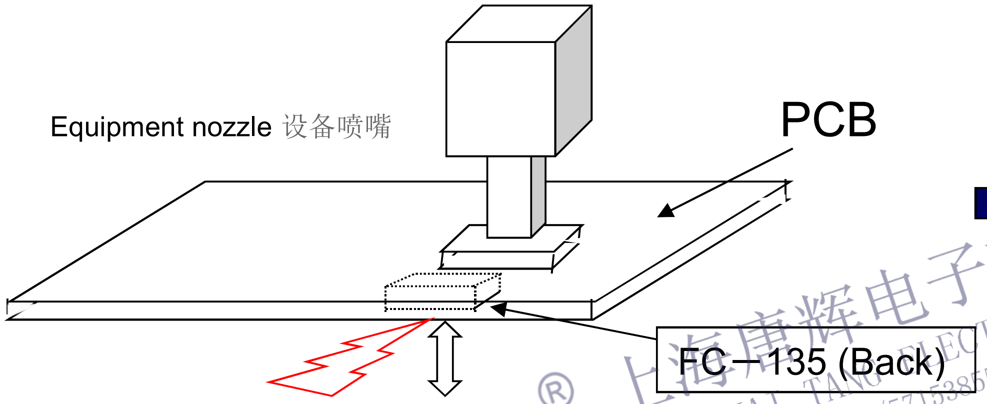
Prevention idea预防方法

- Reexamine the pushing speed
  重新检查推进速度
- Reexamine the pushing amount
  重新检查推入数量
- Change the shape or/and the material of nozzle
  改变喷嘴的形状或者材质



Equipment nozzle shape (metal nozzle) 设备喷嘴形状（金属喷嘴）
Blue shape (large quadrangle) is better than red shape (smallcircle)
There is a risk of Lid peeling happening with red shape. 蓝色形状(大四边形)优于红色形状(小圆形)，红色形状有盖脱落的危险

Appendix - Case .2附录-案例

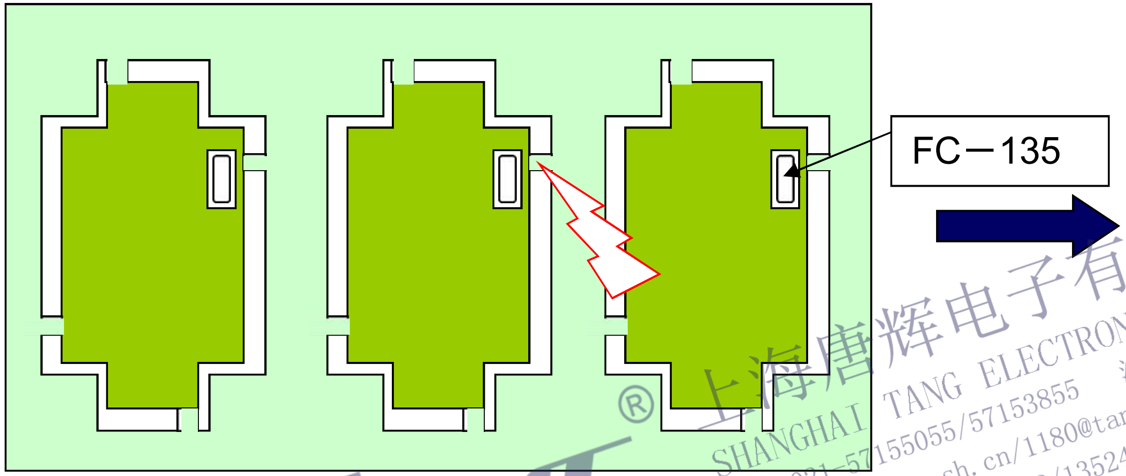


Prevention idea预防方法

- ■ Back evasion 反面规避
- ■ Change the order of assembling 改变装配顺序

Caused by mechanical impact by PCB bending during back side soldering 反面焊接时PCB弯曲引起的机械冲击

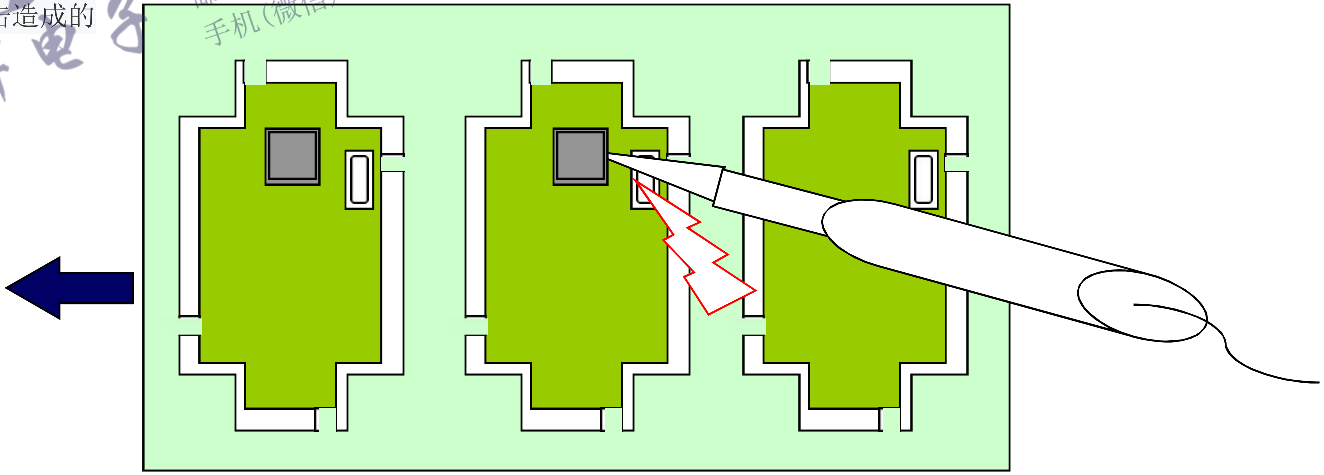
Appendix - Case .3附录-案例



Prevention idea预防方法

- Change the location of FC-135
  改变FC-135的位置

Caused by mechanical impact during PCB separating process 在PCB分离过程中由于机械冲击造成的

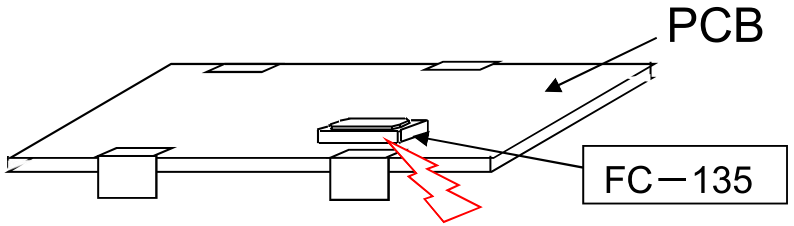


Prevention idea预防方法

- Change the location of FC-135
  改变FC-135的位置

Caused by thermal impact on the glass lid from the iron tip during soldering process 在焊接过程中由热冲击引起的玻璃盖从铁尖上脱落

Appendix - Case .4附录-案例

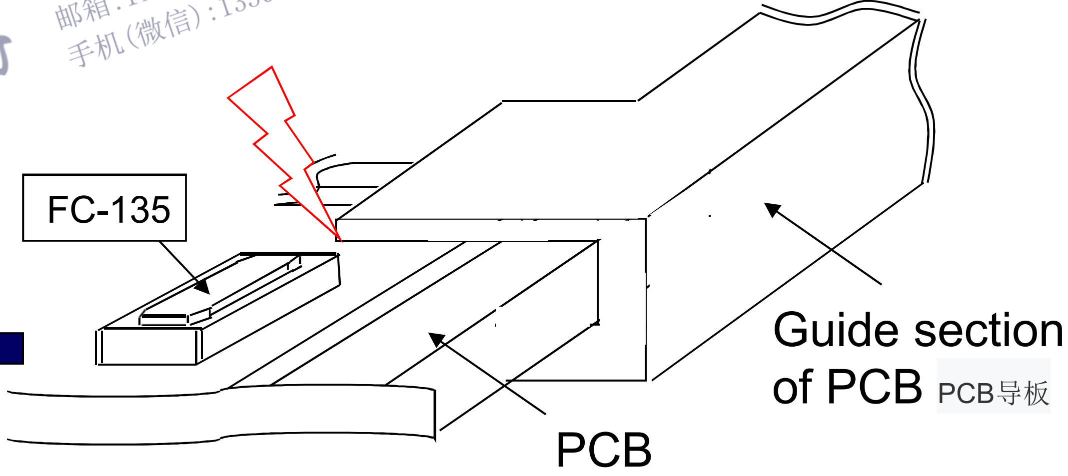


Prevention idea预防方法

- Change the PCB holding material
  更换PCB夹持材料

Caused by mechanical interference to a PCB holding material

由PCB夹持材料的机械干扰引起的



Prevention idea 预防方法

- Change the guide section of PCB
  改变PCB的导板

Caused by mechanical interference to a guide section of PCB 由PCB导板机械干扰引起的